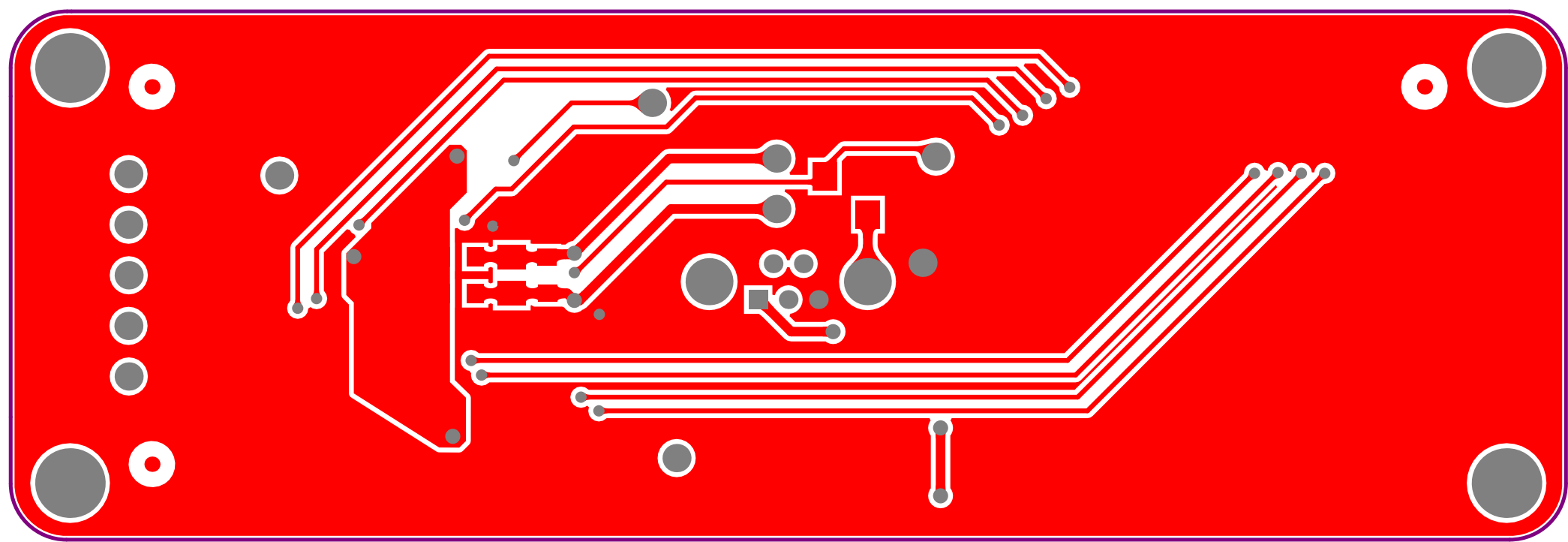
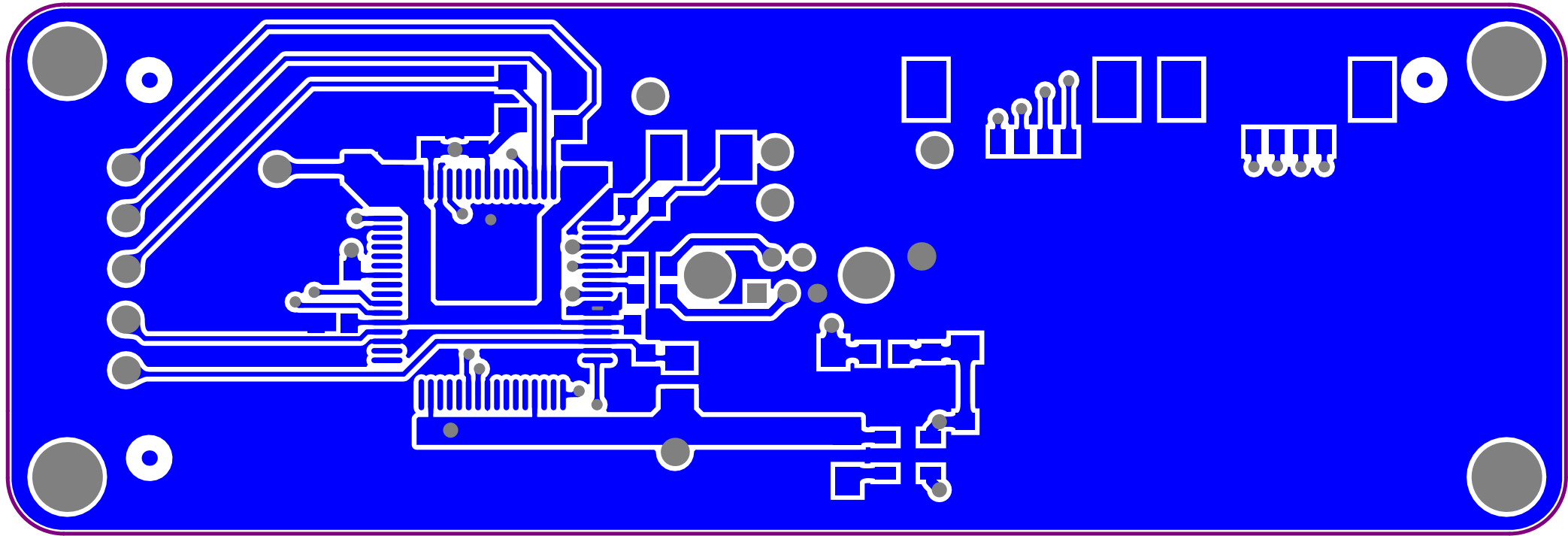


| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0.40mil | 3.8 | |
| 1 | Top Layer | Copper | 1.40mil | | |
| | Dielectric 1 | FR-4 | 59.06mil | 4.5 | |
| 2 | Bottom Layer | Copper | 1.40mil | | |
| | Bottom Solder | Solder Resist | 0.40mil | 3.8 | |
| | Bottom Overlay | | | | |



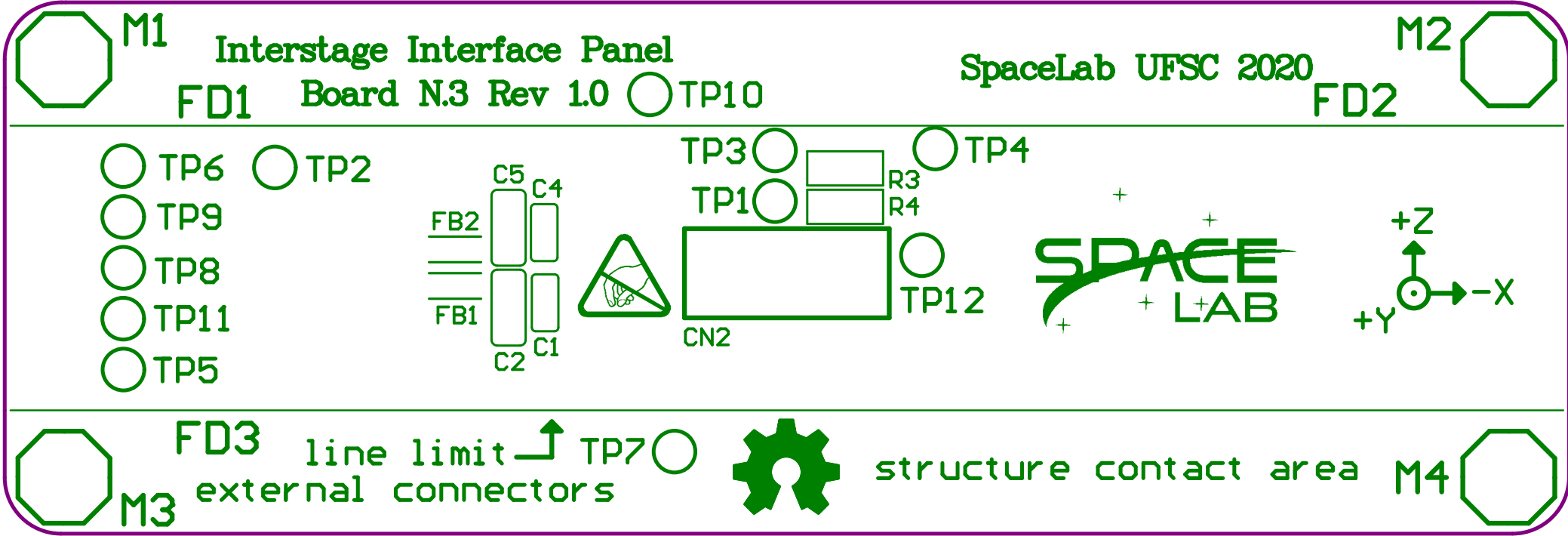
| | | | |
|--------------------------------|----------------------------|---|------------------|
| TITLE: IIP N.3 BOARD QUAD UART | | REV:1.0 | DATE: 15/07/2020 |
| MATERIAL:FR4 | Silkscreen color: white | Project: IIP | |
| Board Thickness:1.6mm | Layers: 02 | Space Technology Research Laboraty Federal University of Santa Catarina SpaceLab UFSC | |
| PCB Surface: HASL | Drawing: Yan C. de Azeredo | | |

| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0.40mil | 3.8 | |
| 1 | Top Layer | Copper | 1.40mil | | |
| | Dielectric 1 | FR-4 | 59.06mil | 4.5 | |
| 2 | Bottom Layer | Copper | 1.40mil | | |
| | Bottom Solder | Solder Resist | 0.40mil | 3.8 | |
| | Bottom Overlay | | | | |



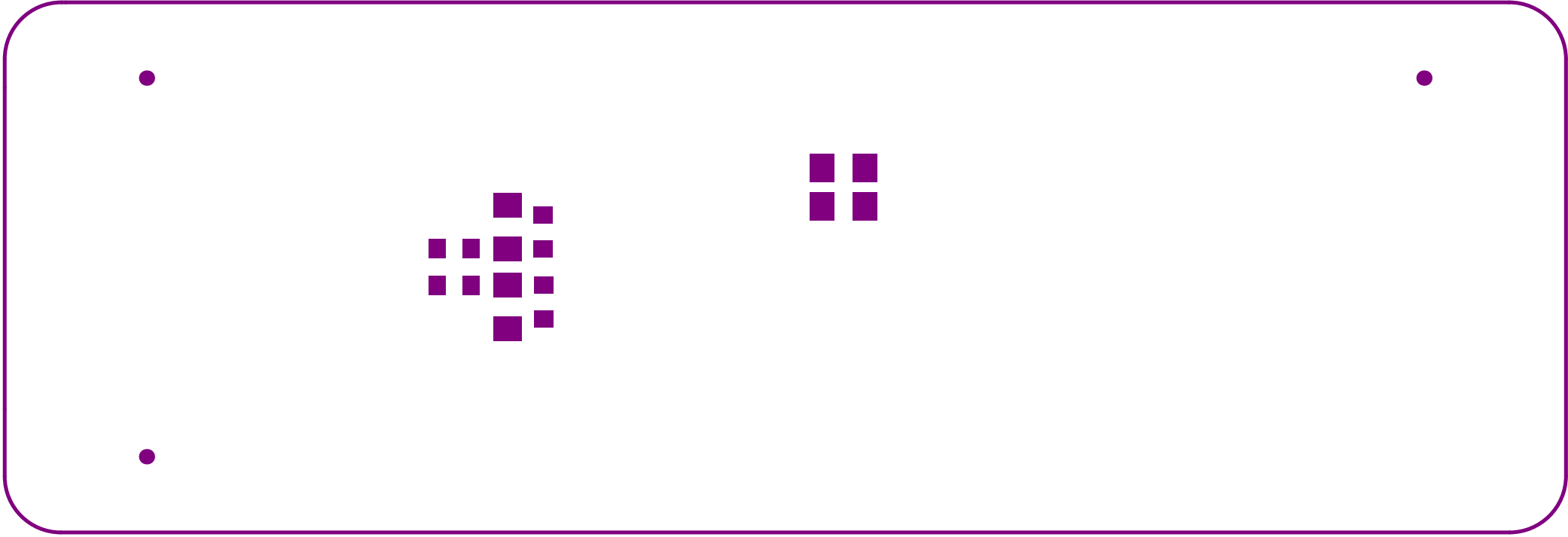
| | | | |
|--------------------------------|----------------------------|---|------------------|
| TITLE: IIP N.3 BOARD QUAD UART | | REV:1.0 | DATE: 15/07/2020 |
| MATERIAL:FR4 | Silkscreen color: white | Project: IIP | |
| Board Thickness:1.6mm | Layers: 02 | Space Technology Research Laboraty Federal University of Santa Catarina SpaceLab UFSC | |
| PCB Surface: HASL | Drawing: Yan C. de Azeredo | | |

| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
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| | Top Solder | Solder Resist | 0.40mil | 3.8 | |
| 1 | Top Layer | Copper | 1.40mil | | |
| | Dielectric 1 | FR-4 | 59.06mil | 4.5 | |
| 2 | Bottom Layer | Copper | 1.40mil | | |
| | Bottom Solder | Solder Resist | 0.40mil | 3.8 | |
| | Bottom Overlay | | | | |



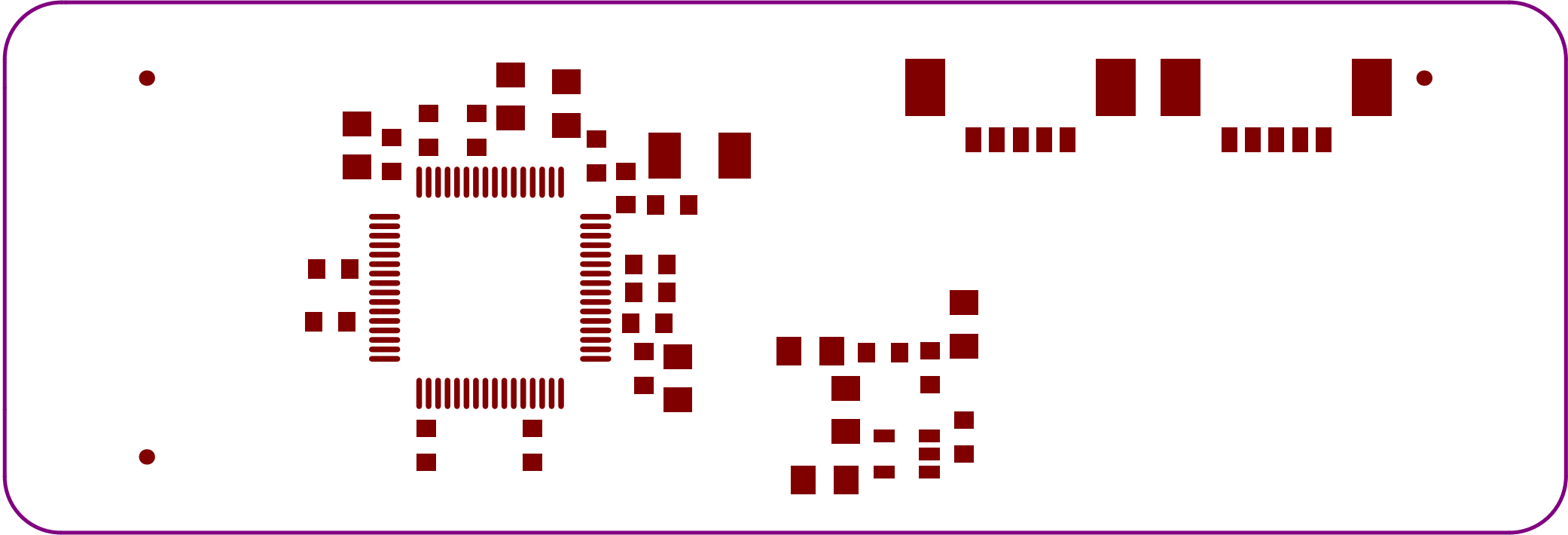
| | | | |
|--------------------------------|----------------------------|---|------------------|
| TITLE: IIP N.3 BOARD QUAD UART | | REV: 1.0 | DATE: 15/07/2020 |
| MATERIAL: FR4 | Silkscreen color: white | Project: IIP | |
| Board Thickness: 1.6mm | Layers: 02 | Space Technology Research Laboraty Federal University of Santa Catarina SpaceLab UFSC | |
| PCB Surface: HASL | Drawing: Yan C. de Azeredo | | |

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| | Dielectric 1 | FR-4 | 59.06mil | 4.5 | |
| 2 | Bottom Layer | Copper | 1.40mil | | |
| | Bottom Solder | Solder Resist | 0.40mil | 3.8 | |
| | Bottom Overlay | | | | |



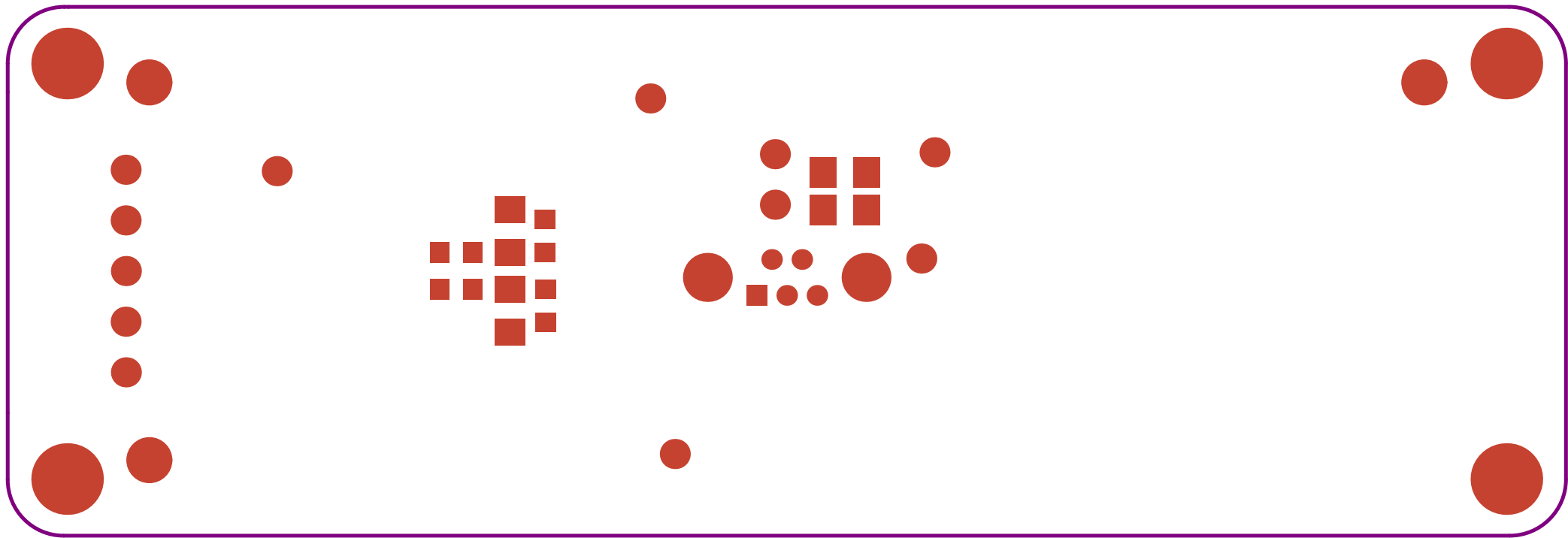
| | | | |
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| TITLE: IIP N.3 BOARD QUAD UART | | REV: 1.0 | DATE: 15/07/2020 |
| MATERIAL: FR4 | Silkscreen color: white | Project: IIP | |
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| PCB Surface: HASL | Drawing: Yan C. de Azeredo | | |

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| | Dielectric 1 | FR-4 | 59.06mil | 4.5 | |
| 2 | Bottom Layer | Copper | 1.40mil | | |
| | Bottom Solder | Solder Resist | 0.40mil | 3.8 | |
| | Bottom Overlay | | | | |



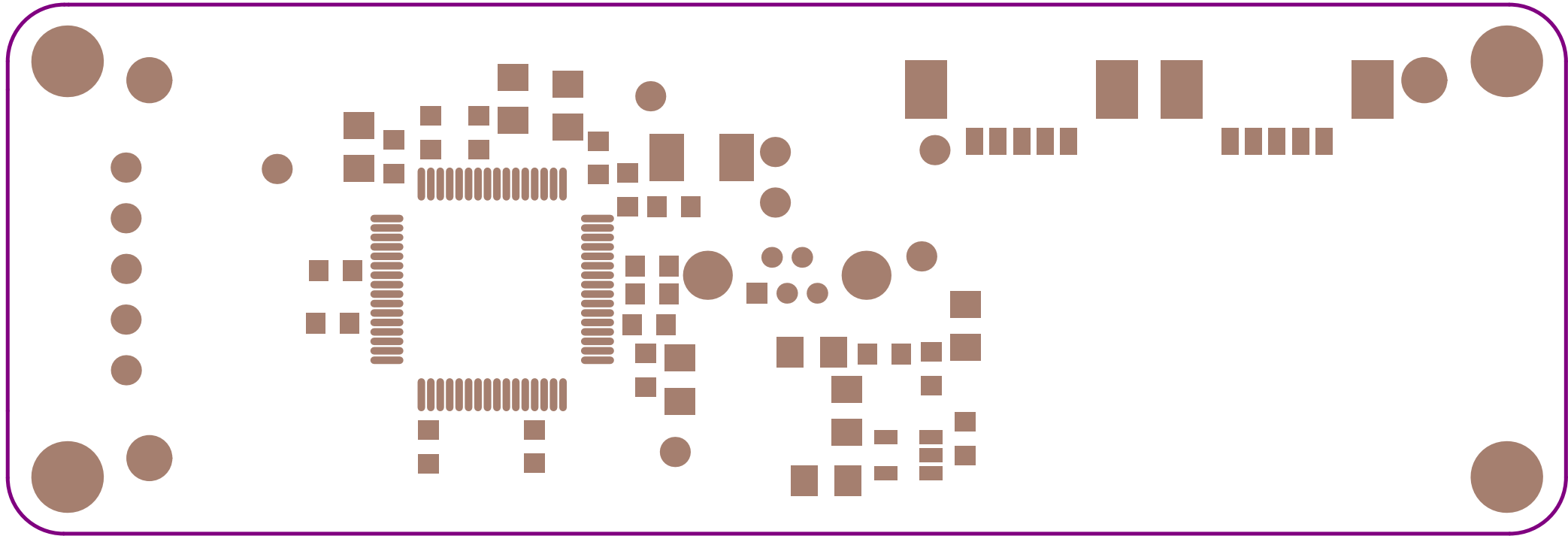
| | | | |
|--------------------------------|----------------------------|---|------------------|
| TITLE: IIP N.3 BOARD QUAD UART | | REV: 1.0 | DATE: 15/07/2020 |
| MATERIAL: FR4 | Silkscreen color: white | Project: IIP | |
| Board Thickness: 1.6mm | Layers: 02 | Space Technology Research Laboraty Federal University of Santa Catarina SpaceLab UFSC | |
| PCB Surface: HASL | Drawing: Yan C. de Azeredo | | |

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|-------|----------------|---------------|-----------|----------|-------------------|
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| 2 | Bottom Layer | Copper | 1.40mil | | |
| | Bottom Solder | Solder Resist | 0.40mil | 3.8 | |
| | Bottom Overlay | | | | |



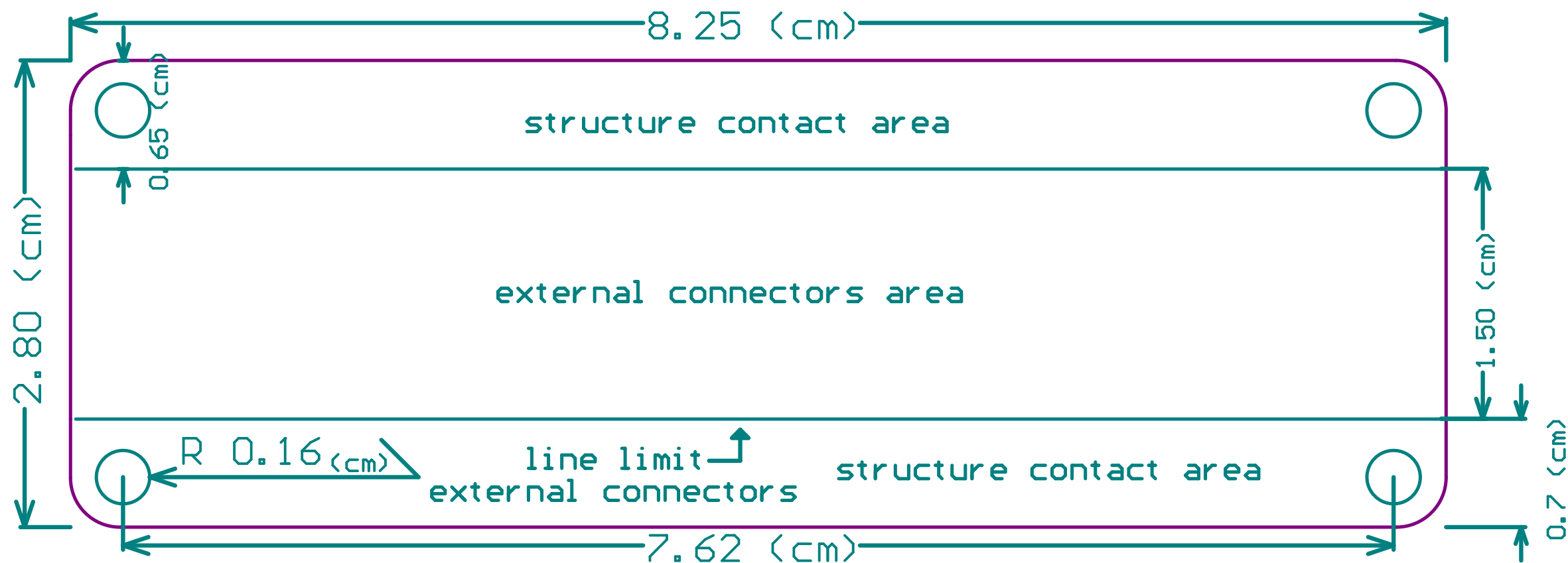
| | | | |
|--------------------------------|----------------------------|---|------------------|
| TITLE: IIP N.3 BOARD QUAD UART | | REV: 1.0 | DATE: 15/07/2020 |
| MATERIAL: FR4 | Silkscreen color: white | Project: IIP | |
| Board Thickness: 1.6mm | Layers: 02 | Space Technology Research Laboraty Federal University of Santa Catarina SpaceLab UFSC | |
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| 2 | Bottom Layer | Copper | 1.40mil | | |
| | Bottom Solder | Solder Resist | 0.40mil | 3.8 | |
| | Bottom Overlay | | | | |



| | | | |
|--------------------------------|----------------------------|---|------------------|
| TITLE: IIP N.3 BOARD QUAD UART | | REV:1.0 | DATE: 15/07/2020 |
| MATERIAL:FR4 | Silkscreen color: white | Project: IIP | |
| Board Thickness:1.6mm | Layers: 02 | Space Technology Research Laboraty Federal University of Santa Catarina SpaceLab UFSC | |
| PCB Surface: HASL | Drawing: Yan C. de Azeredo | | |

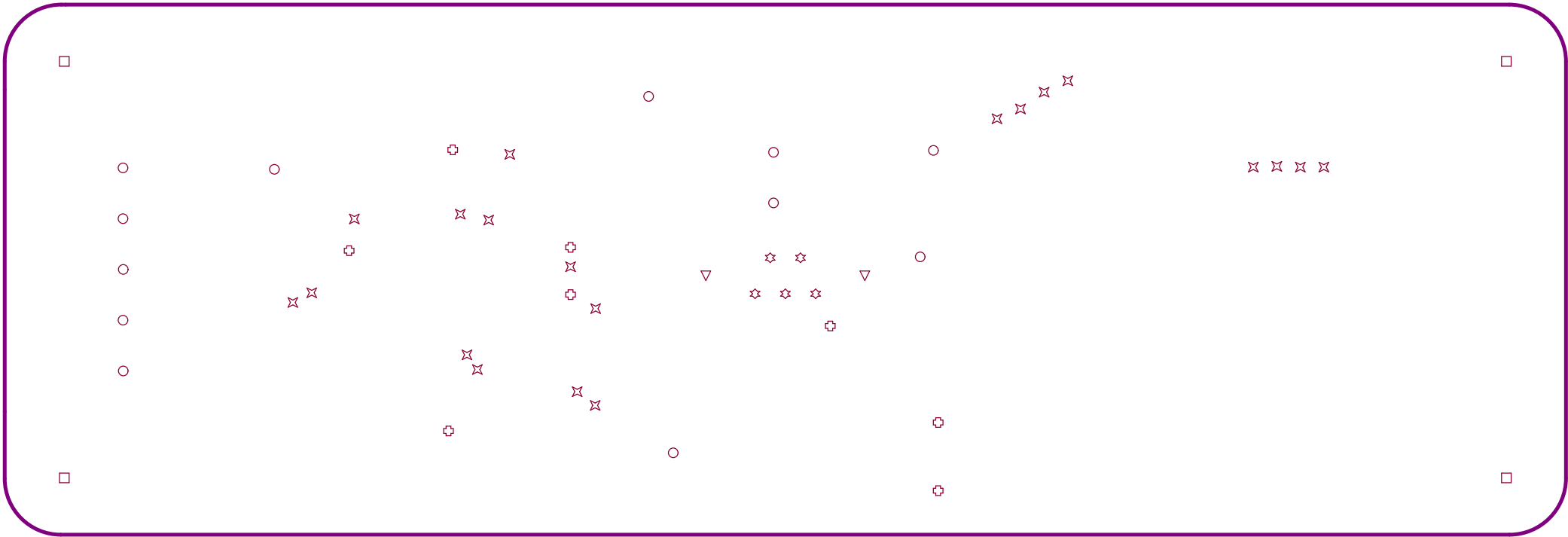
| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0.40mil | 3.8 | |
| 1 | Top Layer | Copper | 1.40mil | | |
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| | Bottom Solder | Solder Resist | 0.40mil | 3.8 | |
| | Bottom Overlay | | | | |



| | | | |
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| TITLE: IIP N.3 BOARD QUAD UART | | REV: 1.0 | DATE: 15/07/2020 |
| MATERIAL: FR4 | Silkscreen color: white | Project: IIP | |
| Board Thickness: 1.6mm | Layers: 02 | Space Technology Research Laboraty Federal University of Santa Catarina SpaceLab UFSC | |
| PCB Surface: HASL | Drawing: Yan C. de Azeredo | | |

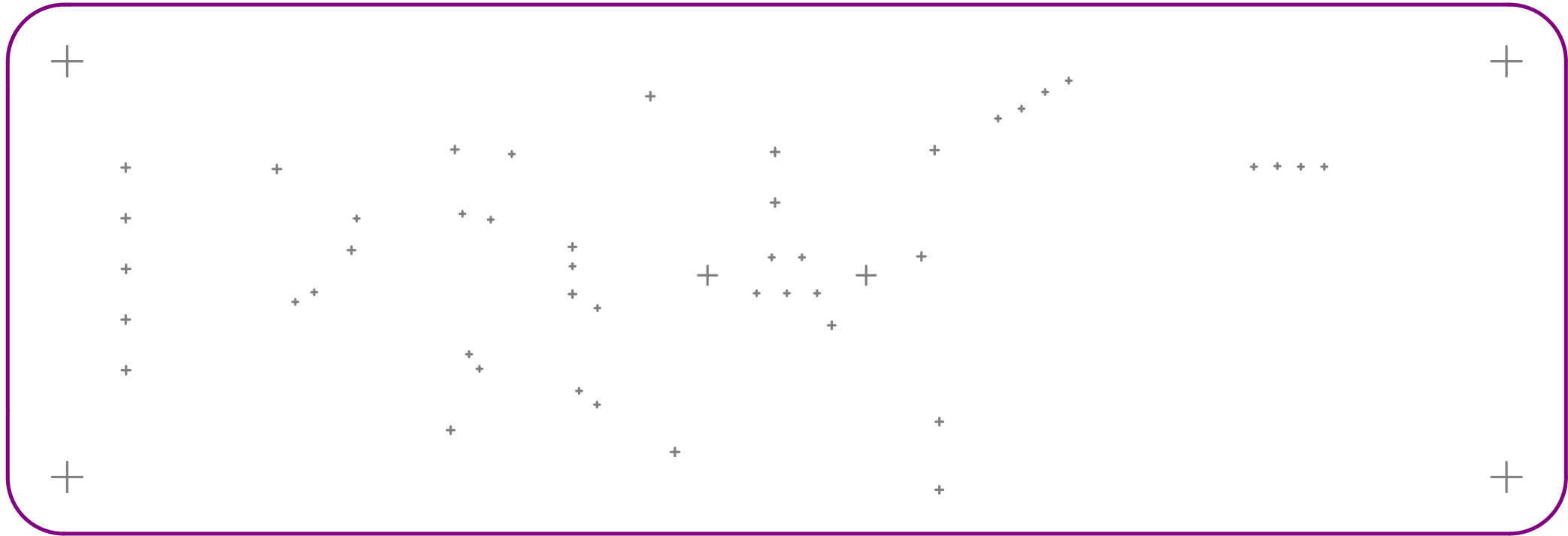
| Symbol | Count | Hole Size | Plated | Hole Type | Drill Layer Pair | Via/Pad | Pad Shape | Template |
|--------|----------|---------------------|--------|-----------|--------------------------|---------|-----------|-------------|
| ✕ | 20 | 0.300mm (11.81mil) | PTH | Round | Top Layer - Bottom Layer | Via | Rounded | v60h30m0mx0 |
| ⊕ | 8 | 0.400mm (15.75mil) | PTH | Round | Top Layer - Bottom Layer | Via | Rounded | v80h40m0mx0 |
| ☆ | 5 | 0.600mm (23.62mil) | PTH | Round | Top Layer - Bottom Layer | Pad | (Mixed) | (Mixed) |
| ○ | 12 | 0.900mm (35.43mil) | PTH | Round | Top Layer - Bottom Layer | Pad | Rounded | c150h90 |
| ▽ | 2 | 2.000mm (78.74mil) | PTH | Round | Top Layer - Bottom Layer | Pad | Rounded | c250h200 |
| □ | 4 | 3.200mm (125.98mil) | PTH | Round | Top Layer - Bottom Layer | Pad | Rounded | c370h320 |
| | 51 Total | | | | | | | |

| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
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| 1 | Top Layer | Copper | 1.40mil | | |
| | Dielectric 1 | FR-4 | 59.06mil | 4.5 | |
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| | Bottom Solder | Solder Resist | 0.40mil | 3.8 | |
| | Bottom Overlay | | | | |



| | | | |
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| TITLE: IIP N.3 BOARD QUAD UART | | REV:1.0 | DATE: 15/07/2020 |
| MATERIAL:FR4 | Silkscreen color: white | Project: IIP | |
| Board Thickness:1.6mm | Layers: 02 | Space Technology Research Laboraty Federal University of Santa Catarina SpaceLab UFSC | |
| PCB Surface: HASL | Drawing: Yan C. de Azeredo | | |

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|-------|----------------|---------------|-----------|----------|-------------------|
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| MATERIAL: FR4 | Silkscreen color: white | Project: IIP | |
| Board Thickness: 1.6mm | Layers: 02 | Space Technology Research Laboraty Federal University of Santa Catarina SpaceLab UFSC | |
| PCB Surface: HASL | Drawing: Yan C. de Azeredo | | |